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On September 8, 2000

TOWNSEND and TOWNSEND and CREW LLP

By:

Sara B. McPeak

PATENT
Attorney Docket No.: 00939-073600US



#9/18
Bill.
9.28.00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sang Young Kim et al.

Application No.: 09/434,736

Filed: November 2, 1999

For: METHOD FOR FILLING
CONTACT HOLES WITH METAL BY
TWO-STEP DEPOSITION

Examiner: E. T. Pert

Art Unit: 2813

AMENDMENT

Assistant Commissioner for Patents
U. S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

This is a response to the Office Action mailed March 9, 2000. A *Petition to Extend Time* to respond from June 9, 2000 to September 9, 2000 is attached hereto. Please amend the above-identified application as follows.

IN THE CLAIMS:

Please amend the following claims as indicated. All pending claims are set forth below for convenient reference.

1. (As Allowed) A method for filling contact holes with metal by two-step deposition of metal layers, said method comprising the steps of:

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